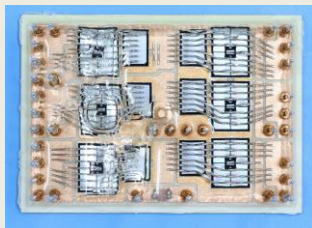
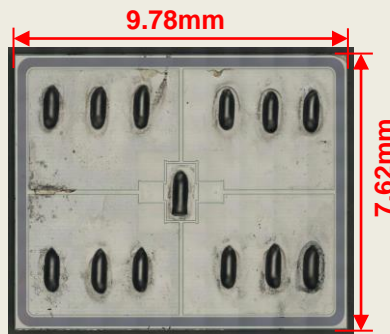


INFINEON EasyPACK™ 7th GEN. IGBT module STRUCTURE and PROCESS ANALYSIS REPORTS

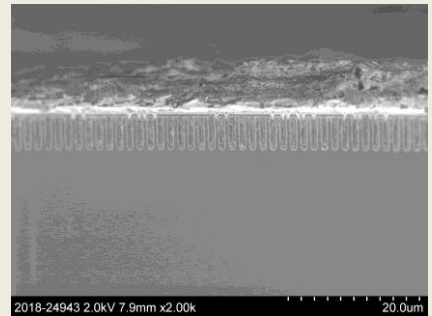
February 2020. LTEC Corporation released a detailed structure and process analysis reports of the S100R12W2T7_B11 7th Gen IGBT module.



Module



Die image



Cross section of the cell area

Product overview

The FS100R12W2T7_B11 is a 1200 V, 100A power module featuring a new high-density Micro Pattern Trench (MPT) design developed to reduce saturation voltage, $V_{ce(sat)}$ from 1.85V to 1.5V by (~19%) relative to 6th Generation device.

Summary of the analysis results

- The unit IGBT cell, formed by a set of seven trenches, and the electrical connection of these trenches is discussed.
- The effective process technology node is extracted from the trench pitch and contact opening. These are the minimum processing dimensions of the manufacturing process technology.
- The off-state collector leakage current of IGBT7 and IGBT6 transistors are measured. A significant difference in activation energy is confirmed.
- The breakdown voltages of the IGBT chip and the parallel-connected FWD are measured.

Note: The report price may change over time. For current price contact info@ltecusa.com.

18G-0017-1

Table of Contents

Structure Analysis Report

Page

Device summary

Table 1, Executive Summary 3

Analysis results summary

Table 2. Device structure 9

Table 3. Material analysis 10

Table 4. Package structure 11

Module analysis

Module overview 13

Die image 17

Module cross section 19

IGBT die analysis

Plane view (optical microscope) 46

Plane view, Scanning Electron Microscope (SEM) 74

Cross-sectional structure analysis (SEM) 87

Electric characteristic

IC-Vce 106

Collect current at of- mode 108

Brake down voltage at off-mode 109

Appendix

EDX results 110

Additional analysis list 136

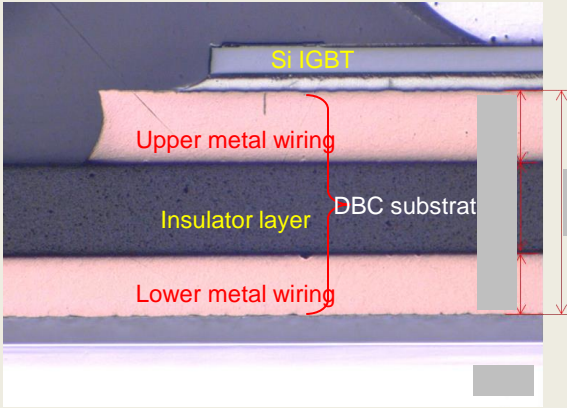
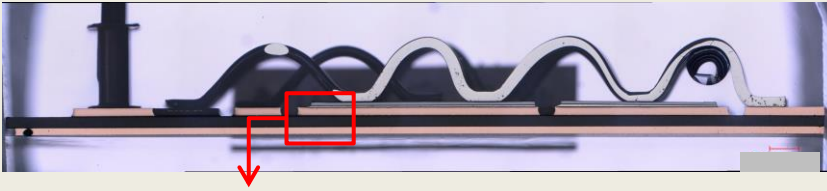


Table of Contents

Process Analysis Report

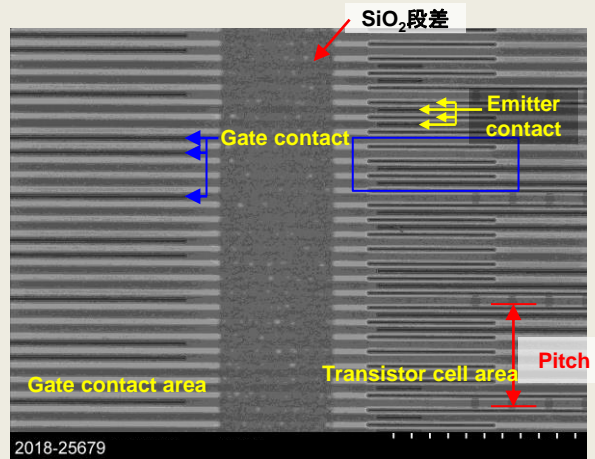
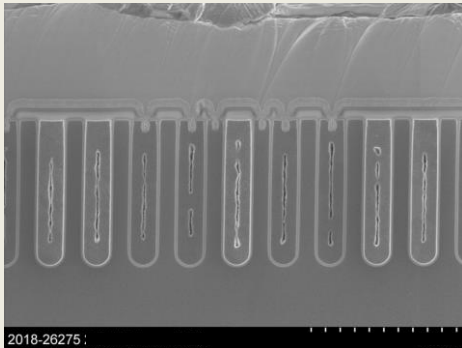
	Page
<u>Analysis summary</u>	3
Comparison summary (Infineon IGBT5, IGBT6 and IGBT7)	4
Module structure (overview)	6
Die overview	7
Device structure IGBT (Cell structure diagram & equivalent schematic)	8
Plain analysis	9
MPT IGBT structure	10
<u>Analysis details</u>	
Plan analysis (die edge)	14
Cross section (die edge)	15
Channel stopper (die edge)	17
Cross section (IGBT array)	20
<u>Process flow (estimation)</u>	
Si IGBT front-end estimated wafer process flow	24
Alignment tree	25
Si IGBT process sequence cross-sectional view	26
Layout	32
<u>Electric characteristic</u>	
IC-Vce characteristics	37
Off-state Collector current	39
Off-state Collector current activation energy (Ea)	42
Off-state breakdown voltage BVces	43
Off-state leakage current comparison (IGBT6 and IGBT7)	44
<u>Appendix</u>	
Reference papers list	45
Reference patents list	46

Excerpts from the Structure Analysis Report



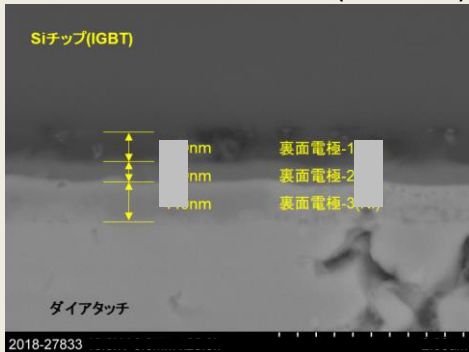
Module cross section

IGBT plane view



Plane SEM image (Gate area)

IGBT structure (Backside)



Excerpts from the Process Analysis Report

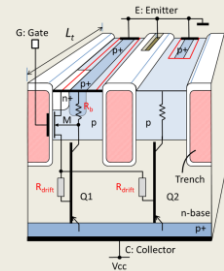
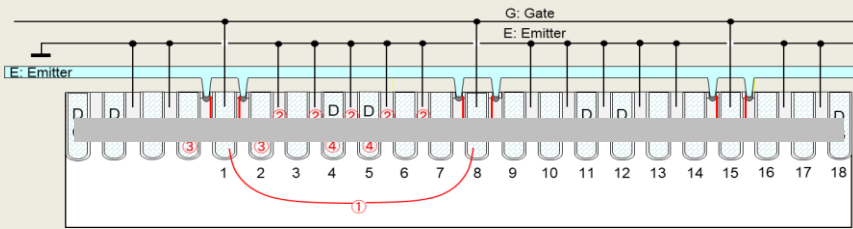
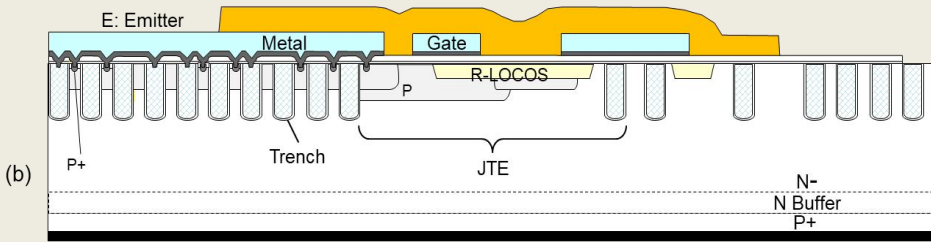
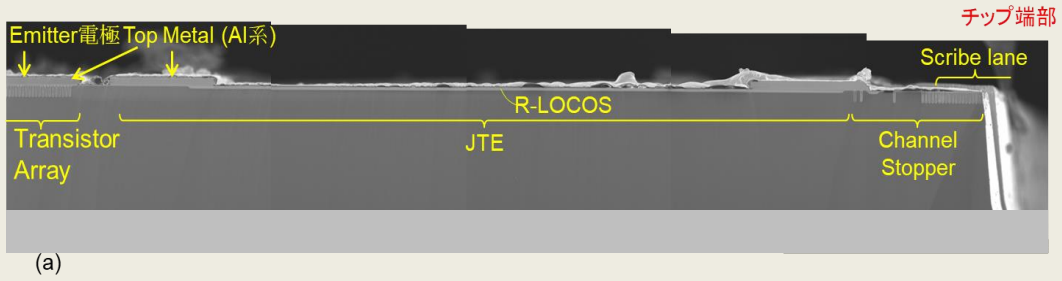
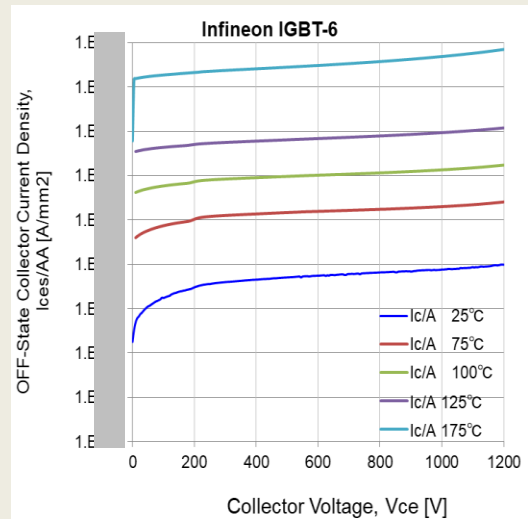
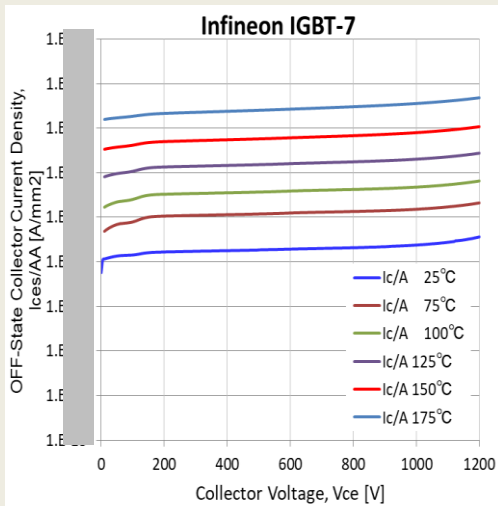


Fig.1-6-1 IGBT7 MPT cell array



Comparison of off-state collect current per cell area (IGBT7 & IGBT6)

Excerpts from the Structure Analysis Report (cont.)

Si IGBT front-end estimated wafer process flow

マスク	プロセス工程	コメント
	ウェーハ	Si FZ N-type 基板 N-(~50-60Ωcm)
	第1酸化	熱酸化
	CVD SiN	LOCOS stack
	FOXコート	FOX: Field Oxide; コーティング: 酸素分子分離絶縁膜
		ss LOCOS
		ension-1 (JT1) Mask
		ension-2 (JT1) Mask
		μm
		化エッチング, ゲートSiO ₂ ~
		S
	PECVDデポ	ILD形成

Si IGBT process sequence cross-sectional view

